

# **Product Disassembly Instructions**

## Product Category: <u>Panel PC</u> Product Marketing Name / Model: <u>PPC-3100S/PPC-3120S/PPC-3150S/PPC-3210SW</u>

**Purpose:** The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq. cm Mother board, Card Reader board, USB Daughter board, LID Daughter board	7
Batteries	All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery	1
External electrical cables and Power cord		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Gas Discharge Lamps		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0

1.1 Items listed below are classified as requiring selective treatment.

Item Description	Notes	Quantity of items included in product
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Capacitors / condensers (Containing PCB)		0

Plastics containing Brominated Flame Retardants weighing > 25 grams	(Not including PCBs or PCAs already listed as a separate item above)	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Asbestos waste and components which contain asbestos		0
Components containing refractory ceramic fibers		0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC)		0
Components, parts and materials containing radioactive substances		0

# 2.0 Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

Disassembly Tool	Picture
Screwdriver	0
Lever	•
Star Screwdriver	0
Hexagon Driver	0
Slanted pliers	
Pliers	-
Hammer	8
Knife	

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials.

#### A. Disassembly Box module.

- A-1. Disassembly 7 pcs screw to remove the MB cover.
- A-2. Disassembly 2 pcs screw to remove the E-eye module.
- A-3. Disassembly 2 pcs screw to separate the E-eye daughter board and bracket.
- A-4. Disassembly 4 pcs screw to remove the HDD/SSD tray from middle cover.
- A-5. Disassembly 4 pcs screw to separate the HDD/SSD and HDD/SSD bracket.
- A-6. Disassembly DDR module from DDR socket.
- A-7. Disassembly mSATA card(2pcs screw) and Mini PCIe card(2pcs screw) from each socket.
- A-8. Remove RTC battery wire cable.
- A-9. Disassembly Hex 4pcs from COM port, screw 4pcs from mother board to separate the mother board and chassis.
- A-10. Disassembly 2pcs antenna rubber cap from MB cover.
- A-11. Disassembly 2 pcs screw to remove the antenna bracket from middle cover.

#### **B. Disassembly Panel module.**

- B-1. Disassembly screw 8pcs to remove the middle cover.
- B-2. Disassembly screw 1pcs to remove the LED indicator board.
- B-3. Disassembly screw 4pcs to remove the LCD sub-assembly from Front Bezel.
- B-4. Disassembly screw 4pcs to separate the LCD bracket left and right with LCD module.
- B-5. Separate the LCD sponge from LCD opening bezel.
- B-6. Remove the waterproof from front bezel.

3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

